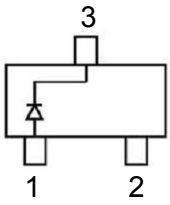
FEATURES

Planar Die Construction.
300mW Power Dissipation.
Zener Voltages from 2.4V - 43V.
Ultra-Small Surface Mount Package Power Dissipation

SOT-23



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
BZX84C2V4-BZX84C43	SOT-23	XXX	3000

XXX=Device code, see table on page2 the marking code.

Absolute Maximum Ratings(Ta=25℃)

Symbol	Parameter	Value	Unit
V_F	Forward Voltage (Note 2) @ I_F=10mA	0.9	V
P_d	Power Dissipationn (Note 1)	200	mW
$R_{\Theta JA}$	Thermal Resistance From Junction To Ambient	625	℃/W
T_J	Operation Junction Temperature Range	-40~+125	℃
T_{STG}	Storage Temperature Range	-55~+150	℃

Electrical Characteristics (T a =25 ℃ unless otherwise specified)

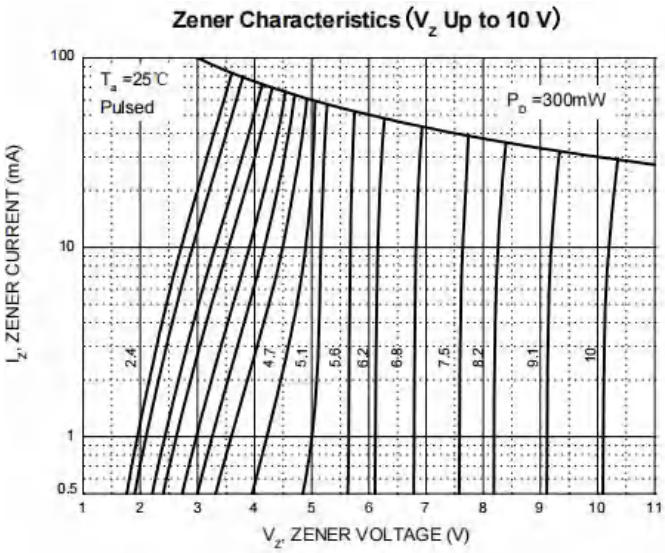
TYPE	Marking	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I_{ZT}=5mA mV/℃	
		V_Z @I_{ZT} (V)			I_{ZT} (mA)	V_Z @I_{ZT}	V_Z @I_{ZK}	I_{ZK} (mA)	I_R	V_R		
		Nom	Min	Max		Ω			μA	V	Min	Max
BZT52C2V4	Z11	2.4	2.2	2.6	5	100	600	1.0	50	1.0	-3.5	0
BZT52C2V7	Z12	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
BZT52C3V0	Z13	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
BZT52C3V3	Z14	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0
BZT52C3V6	Z15	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0
BZT52C3V9	Z16	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V3	Z17	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V7	Z1	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2
BZT52C5V1	Z2	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2
BZT52C5V6	Z3	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2.0	2.5
BZT52C6V2	Z4	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7
BZT52C6V8	Z5	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5
BZT52C7V5	Z6	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3
BZT52C8V2	Z7	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2
BZT52C9V1	Z8	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0
BZT52C10	Z9	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0
BZT52C11	Y1·	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
BZT52C12	Y2·	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
BZT52C13	Y3	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
BZT52C15	Y4	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
BZT52C16	Y5	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
BZT52C18	Y6·	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
BZT52C20	Y7	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
BZT52C22	Y8	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
BZT52C24	Y9	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
BZT52C27	Y10	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
BZT52C30	Y11·	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4
BZT52C33	Y12	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4
BZT52C36	Y13	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4
BZT52C39	Y14	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2
BZT52C43	Y15	43	40.0	46.0	2	100	700	1	0.1	32.0	10.0	12.0

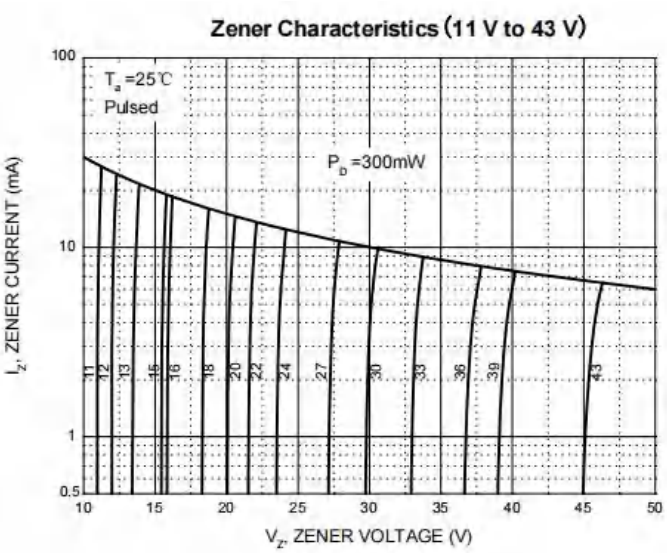
Notes: 1. Valid provided that device terminals are kept at ambient temperature.

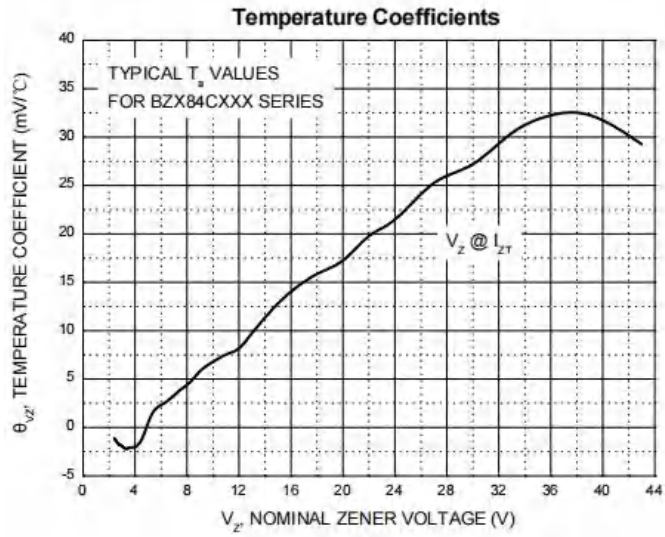
2. Tested with pulses, period=5ms,pulse width =300μs.

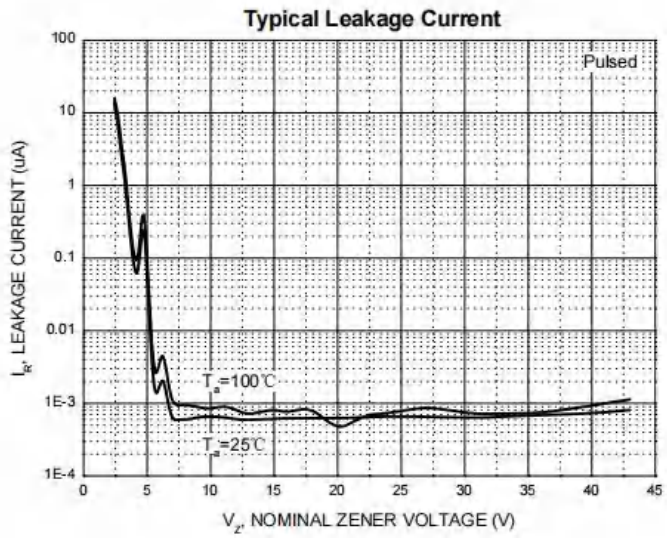
3. f = 1kHz.

Typical Characteristics

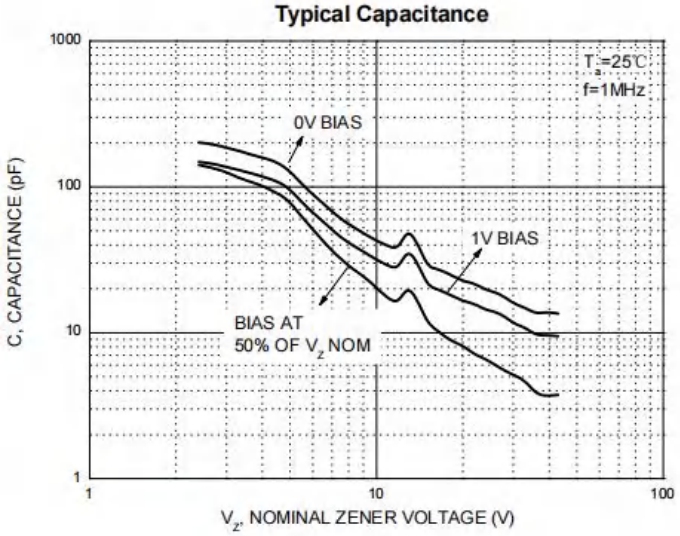




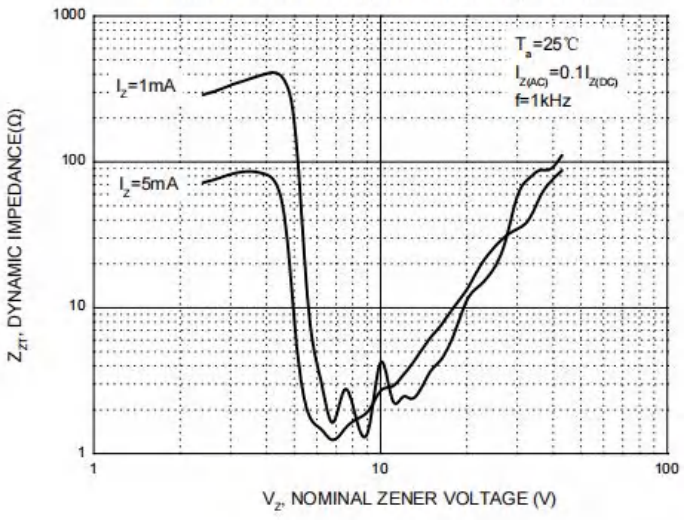




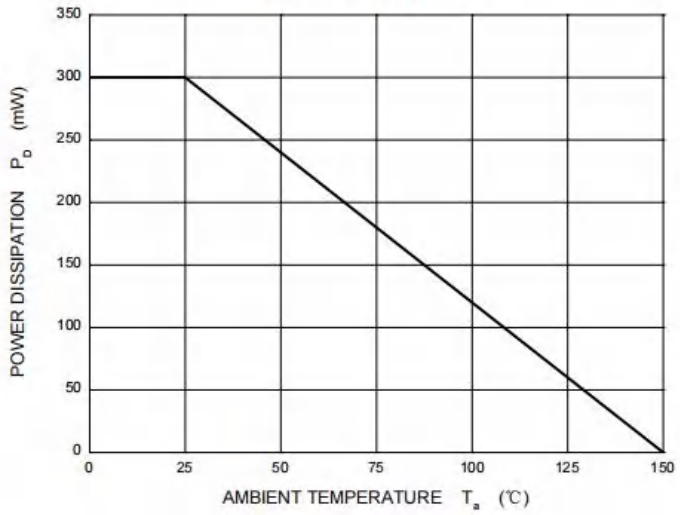
Typical Capacitance



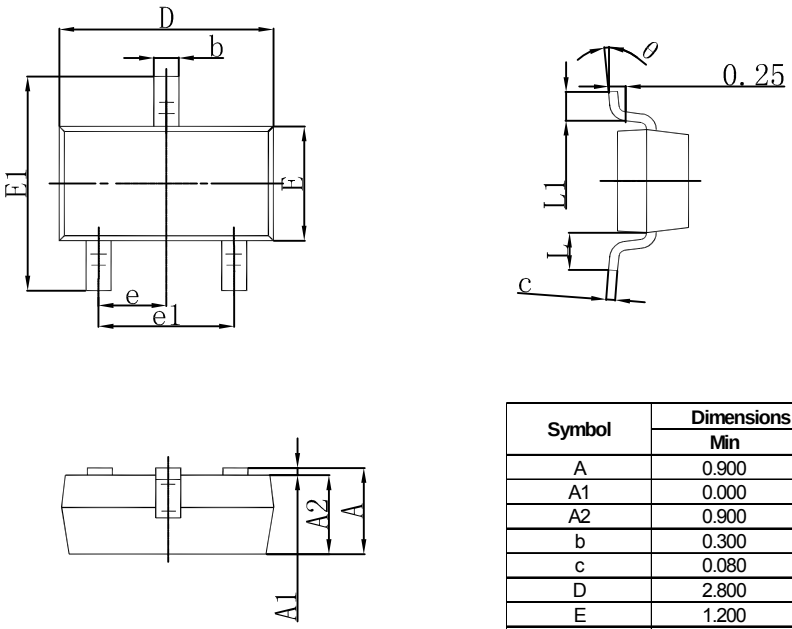
Effect of Zener Voltage on Zener Impedance



Power Derating Curve

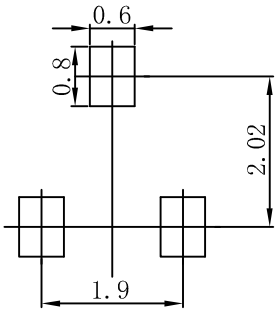


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

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